

# High Precision Micro Cutting

with an Ultra-short Pulse Laser

- Feature1 High-quality processing without thermal strain and burr is possible
- Feature2 Possible to support high hardness materials, difficult-to-cut materials and brittle materials regardless of their properties
- Feature3 Groove, sequence etching and other non-penetration processing is possible in addition to piercing and complete cutting

## Processing Examples by Material

SUS304

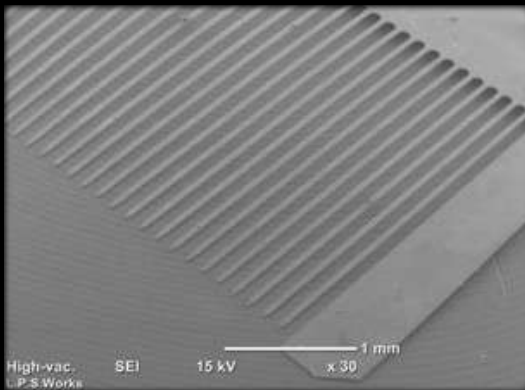


Plate thickness: 10  $\mu$ m / Gap: 100  $\mu$ m

Polyimide

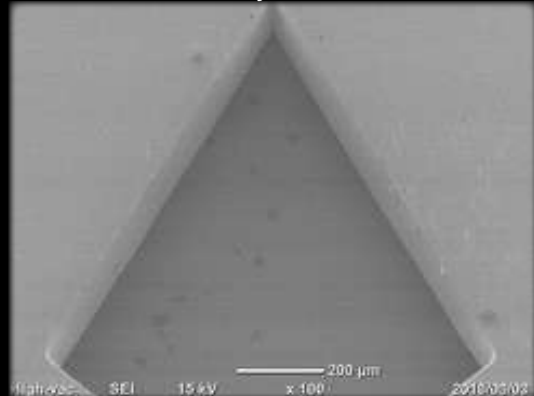


Plate thickness: 125  $\mu$ m

Tungsten

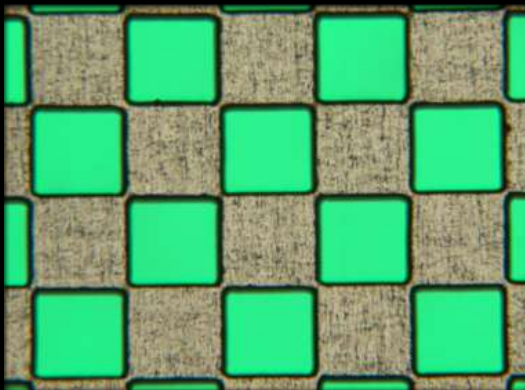


Plate thickness: 100  $\mu$ m /  $\square$  300  $\mu$ m

Zirconia

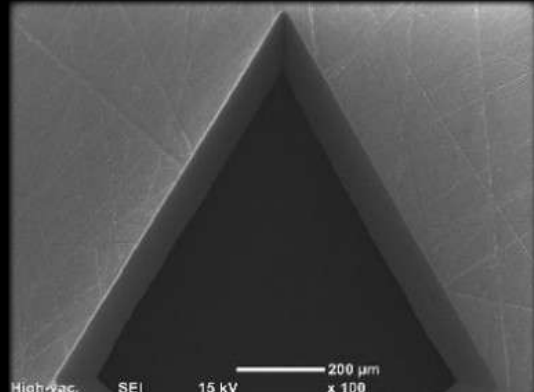


Plate thickness: 300  $\mu$ m

SUS

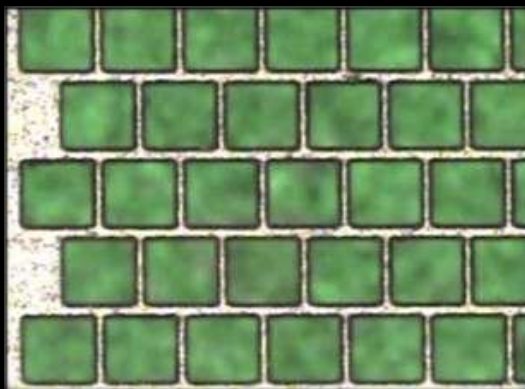


Plate thickness: 50  $\mu$ m / Gap: 20  $\mu$ m

Cu

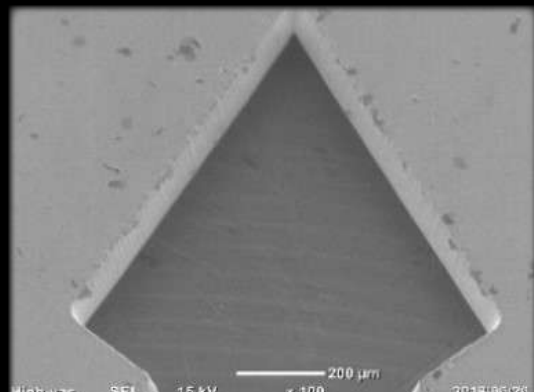


Plate thickness: 100  $\mu$ m



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